

**Date:** February 2021  
**Rev:** IX  
**No. of Components:** Single  
**Mix Ratio by Weight:** N/A  
**Specific Gravity:** 3.51  
**Pot Life:** 2 Weeks  
**Shelf Life- Bulk:** One year at -40°C

**Recommended Cure: 150°C / 1 Hour plus 200°C / 1 Hour**

**Minimum Alternative Cure(s):**  
*May not achieve performance properties listed below*  
 200°C / 30 Minutes  
 150°C / 1 Hour

### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** A longer dry time and low viscosity version of EPO-TEK® EK1000 designed for applications requiring longer working time and better flowing than provided by EPO-TEK® EK1000.

**Typical Properties:** Cure condition: 150°C / 1 Hour plus 200°C / 1 Hour      Different batches, conditions & applications yield differing results.  
 To be used as a guide only, not as a specification.      \* denotes test on lot acceptance basis      Data below is not guaranteed.

PHYSICAL PROPERTIES:			
* Color (before cure):	Silver		
* Consistency:	Smooth thixotropic paste		
* Viscosity (23°C) @ 100 rpm:	1,800 - 3,300	cPs	
Thixotropic Index:	4.8		
* Glass Transition Temp:	≥ 70	°C (Dynamic Cure: 20-300°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)	
Coefficient of Thermal Expansion (CTE):			
	Below Tg:	41	x 10 <sup>-6</sup> in/in°C
	Above Tg:	162	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	65		
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	372 °C		
Weight Loss:			
	@ 200°C:	0.03	%
	@ 250°C:	0.40	%
	@ 300°C:	1.00	%
Suggested Operating Temperature:	< 300 °C (Intermittent)		
Storage Modulus:	609,195 psi		
Ion Content:			
	Cl <sup>-</sup> :	6 ppm	Na <sup>+</sup> : 3 ppm
	NH <sub>4</sub> <sup>+</sup> :	8 ppm	K <sup>+</sup> : 2 ppm
* Particle Size:	≤ 45 microns		

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity (150°C / 1 Hour plus 200°C / 1 Hour):	22.7	W/mK
Thermal Conductivity (150°C / 1 Hour):	12.1	W/mK
Volume Resistivity @ 23°C:	≤ 0.00008 x 10	Ohm-cm

**This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.**

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